

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4147161

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| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                           |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                               |
| <b>CONVEYING PARTY DATA</b>   |  |
| <b>Name</b>   | <b>Execution Date</b>                    |
| MICRON TECHNOLOGY, INC.   | 09/26/2008                               |
| <b>RECEIVING PARTY DATA</b>   |  |
| <b>Name:</b>  | APTINA IMAGING CORPORATION               |
| <b>Street Address:</b>  | C/O CITICO TRUSTEES (CAYMAN) LIMITED     |
| <b>Internal Address:</b>  | REGATTA OFFICE PARK, WEST BAY ROAD       |
| <b>City:</b>  | GRAND CAYMAN                             |
| <b>State/Country:</b>   | CAYMAN ISLANDS                           |
| <b>Postal Code:</b>   | Y1-1205                                  |
| <b>PROPERTY NUMBERS Total: 1</b>  |  |
| <b>Property Type</b>  | <b>Number</b>                            |
| Patent Number:  | 7723140                                  |
| <b>CORRESPONDENCE DATA</b>  |  |
| <b>Fax Number:</b>  | (602)244-3169                            |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |  |
| <b>Phone:</b>   | 6022443574                               |
| <b>Email:</b>   | patents@onsemi.com                       |
| <b>Correspondent Name:</b>  | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC |
| <b>Address Line 1:</b>  | 5005 E. MCDOWELL ROAD                    |
| <b>Address Line 2:</b>  | MAILDROP A700                            |
| <b>Address Line 4:</b>  | PHOENIX, ARIZONA 85008                   |
| <b>ATTORNEY DOCKET NUMBER:</b>  | APT2003-0213D01                          |
| <b>NAME OF SUBMITTER:</b>   | SHARRON CASTILLO                         |
| <b>SIGNATURE:</b>   | /Sharron Castillo/                       |
| <b>DATE SIGNED:</b>   | 11/17/2016                               |
| <b>Total Attachments: 7</b>   |  |
| source=APT2003-0213D01_20161117_Assignment_MicronAptina#page1.tif   |  |
| source=APT2003-0213D01_20161117_Assignment_MicronAptina#page2.tif   |  |
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| source=APT2003-0213D01_20161117_Assignment_MicronAptina#page4.tif   |  |

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PATENT ASSIGNMENT AGREEMENT

1. Definitions

(a) "Agreement" shall mean this Patent Assignment Agreement.

(b) "Assignee" shall mean **Aptina Imaging Corporation**, a Cayman Islands corporation with offices at c/o Citcoo Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.

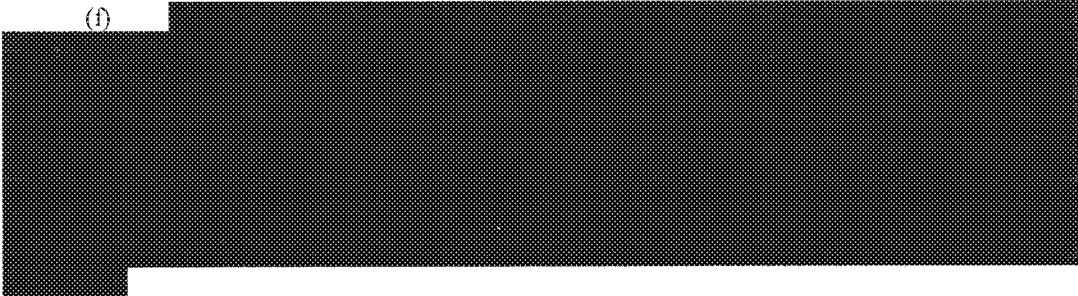
(c) "Assignor" shall mean **Micron Technology, Inc.**, a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.

(d) "Effective Date" shall mean October 3, 2008.

(e)



(f)



(g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(k) [REDACTED]

2. [REDACTED]

(a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee and to record assignment of the Imaging Patents to Assignee.

(b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.

(c) [REDACTED]

(d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee and to record assignment of the Semiconductor Patents to Assignee.

(e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, [REDACTED] Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.

(f)

[REDACTED]

[REDACTED]

[REDACTED]

3 [REDACTED]

[REDACTED]

4. [REDACTED]

[REDACTED]

5. [REDACTED]

[REDACTED]

[REDACTED]

6. [REDACTED]

[REDACTED]

7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

[the rest of this page intentionally left blank]

Agreed to by:

Micron Technology, Inc.

Signed: [Signature]

Date: 9/26/08, 2008

Notarization  
State of Idaho  
County of Ada

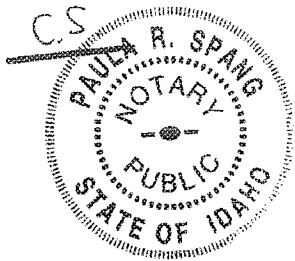
On 9/26/08 before me, Paula R. Spang, personally appeared the above-named Steven R. Appleton

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11

REVIEWED  
MTI LEGAL



Agreed to by:

Aptina Imaging Corporation

Signed: Thomas L. Lowe, Jr.

Date: 9/26/08, 2008

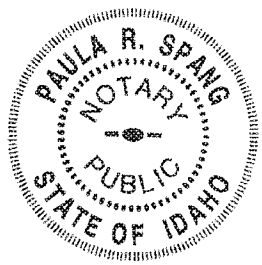
Notarization  
State of Idaho  
County of Ada

On 9/26/08 before me, Paula R. Spang, personally appeared the above-named Thomas L. Lowe, Jr.

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11



[Signature page to the Patent Assignment Agreement]

ATTACHMENT "B"  
IMAGING PATENT APPLICATIONS



## Aptina Applications

| FILE NUMBER     | TITLE  | STATUS    | COUNTRY NAME             | APPLICATION NUMBER | DATE FILED   |
|-----------------|--|-----------|--------------------------|--------------------|--------------|
| 2003-0194.00/PC | IMAGE PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY     | Completed | PCT                      | pct.us0424598      | Jul 30, 2004 |
| 2003-0194.00/SG | AN IMAGER PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY | Pending   | Singapore                | 2006007845         | Jul 30, 2004 |
| 2003-0194.01/CH | IMAGE PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY     | Pending   | China                    | 2008100957669      | Jul 30, 2004 |
| 2003-0194.02/US | AN IMAGE PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY  | Abandoned | United States of America | 11268773           | Nov 8, 2005  |
| 2003-0213.00/US | PIXEL CELL WITH A CONTROLLED OUTPUT SIGNAL KNEE CHARACTERISTIC RESPONSE              | Pending   | United States of America | 10881525           | Jul 1, 2004  |
| 2003-0213.01/US | PIXEL CELL WITH A CONTROLLED OUTPUT SIGNAL KNEE CHARACTERISTIC RESPONSE              | Pending   | United States of America | 11589205           | Oct 30, 2006 |
| 2003-0241.00/CH | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Pending   | China                    | 2004600307584      | Aug 18, 2004 |
| 2003-0241.00/EP | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Pending   | European Patent Office   | 047815385          | Aug 18, 2004 |
| 2003-0241.00/JP | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Pending   | Japan                    | 2006524727         | Aug 18, 2004 |
| 2003-0241.00/KR | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Pending   | Republic of Korea        | 20067003589        | Aug 18, 2004 |
| 2003-0241.00/PC | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Completed | PCT                      | PCTUS200426876     | Aug 18, 2004 |
| 2003-0241.00/SG | IMAGING WITH GATE CONTROLLED CHARGE STORAGE  | Pending   | Singapore                | 2006011124         | Aug 18, 2004 |

